

PRODUCT DATA SHEET

QuickSinter® QS815-SD

Pressureless Silver Sintering Paste

Introduction

Indium Corporation's **QS815-SD Silver Sintering Paste** is a high metal-loading material designed to fit easily into a dispensing process with no change in deposition equipment. The paste can also use fast "reflow-like" (RFL) sintering processes to form strong joints on many standard leadframe, DBC, and IPM pad finishes, and will bond strongly to die with Ag, Au, or Cu surfaces depending on sintering atmosphere and profile. **QS815-SD** is the easy-to-dispense pressureless silver sintering formulation.

Solder and many standard epoxy-silver materials are proving increasingly unsuitable for many discrete and small module device applications (i.e., incapable of surviving the ambient

conditions seen during longer mission profiles in automotive applications). These mission profiles may drive a longer high-temperature operating life (HTOL) and larger temperature swings during usage (thermal cycling).

Dispense: The silver sintering paste is capable of being dispensed at very high speed (>3 dots/second) using readily available needles and a variety of unique dispense patterns with ease. 18–32-gauge needles were tested.

Sinter: Smaller die are typically better suited to faster-ramping RFL sintering (guidelines below).

Features

- Die size: $\leq 2 \times 2$ mm
- Pressureless sintering paste; also suited to pressurized sintering
- Quick: sinterable within 12 minutes, compatible with inline reflow oven
- Can be used on Cu-, Ag-, and Au-finished surface
- No voiding or very low voiding (<2%) on a silver sintering joint with high shear strength (>30MPa)
- High electrical conductivity
- High thermal conductivity
- RoHS-compliant
- Long shelf life
- Long work life
- Not considered a nanomaterial per EU definition (2011/696/EU)

Typical Properties of Paste Before and After Sintering

Properties	QS815-SD
Before sintering	
Ag content, wt%	92
Viscosity, kcps, 5rpm at 25°C	12.6
Paste application method	Dispensing
After sintering	
Melting point (°C)	961
Electrical resistivity ($\mu\Omega\cdot\text{cm}$)	5
Thermal conductivity (W/mK)	>200
CTE (ppm/K)	19

Application

QS815-SD is most commonly used as a die-attach material in devices such as discrete, high power IGBT, MOSFET, and semiconductor diodes. It is designed for Pb-free joints requiring high thermal and electrical conductivity, as well as high service temperature. Silver sintering paste maintains high adhesion and tensile strength at operating temperatures >350°C.

From One Engineer To Another®



Form No. 99781 R1

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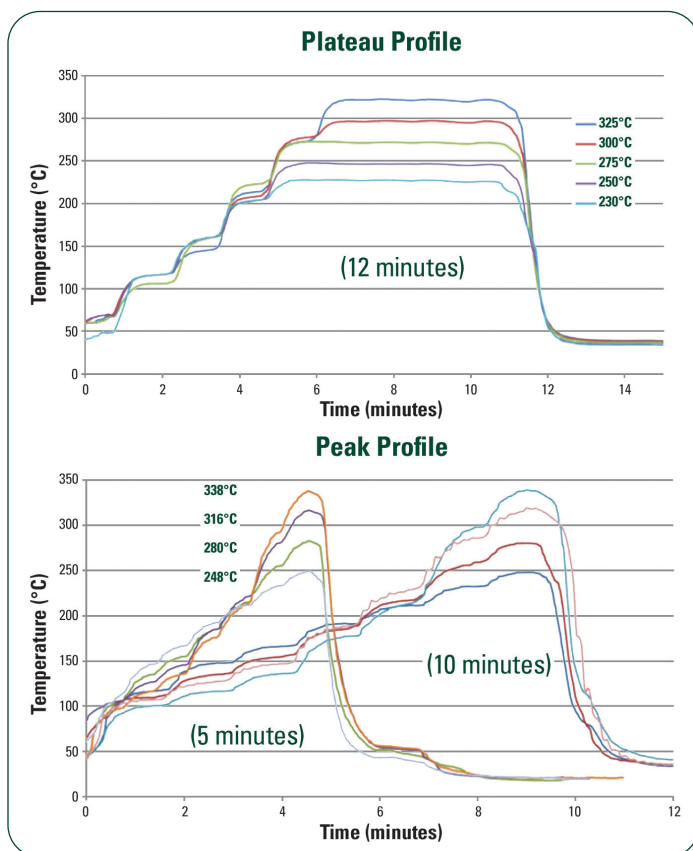
Pressureless Silver Sintering Paste

Sintering Example and Result

The profiles recommended below are guidelines. Temperatures are measured at joints.

Quick Pressureless Sintering with BTU Reflow Oven

The experiments are conducted in a BTU reflow oven, in air, using the following profiles:



Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice on Ag sintering applications. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

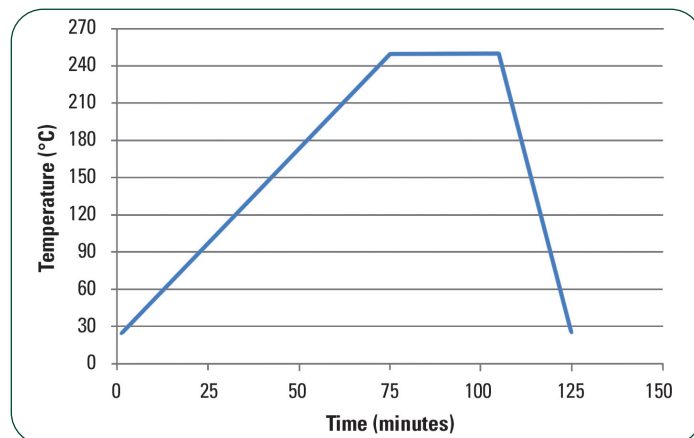
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Box Oven Pressureless Sintering

The experiments are conducted in air using the following profile:



Storage and Handling Procedure

Refrigerated storage will prolong the shelf life of Ag sintering paste (>6 months). The shelf life of the paste is 6 months when sealed tightly and stored at <-20°C. Ag sintering paste packaged in syringe should be stored tip down.

Ag sintering paste should be allowed to reach ambient working temperature prior to use. Generally, paste should be removed from refrigeration at least 1 hour before use. Actual time to reach thermal equilibrium will vary with container size. Paste temperature should be verified before use. Syringes and jars should be labeled with date and time of opening.

Packaging

Ag sintering paste is available in syringes or jars.

Safety Data Sheet

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.



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